

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT7642220

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HOUSSAM CHOUAIB	10/25/2019
DAWEI HU	11/05/2019
KAI-HSIANG LIN	11/12/2019
AARON ROSENBERG	10/25/2019
ZHENGQUAN TAN	11/13/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	KLA CORPORATION
<b>Street Address:</b>	ONE TECHNOLOGY DRIVE
<b>Internal Address:</b>	SUITE 407
<b>City:</b>	MILPITAS
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95035
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17338449
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	650 307 0332
<b>Email:</b>	isabelle@spanolawgroup.com
<b>Correspondent Name:</b>	SPANO LAW GROUP
<b>Address Line 1:</b>	851 BURLWAY ROAD
<b>Address Line 2:</b>	SUITE 407
<b>Address Line 4:</b>	BURLINGAME, CALIFORNIA 94010
<b>ATTORNEY DOCKET NUMBER:</b>	KLA-126-1C (P5425CON2)
<b>NAME OF SUBMITTER:</b>	JOSEPH S. SPANO
<b>SIGNATURE:</b>	/JOSEPH S. SPANO/
<b>DATE SIGNED:</b>	11/13/2022

**Total Attachments: 6**

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source=KLA-126-P5425-Assignment-Rosenberg-signed#page1.tif

source=KLA-126-P5425-Assignment-Tan-signed#page1.tif

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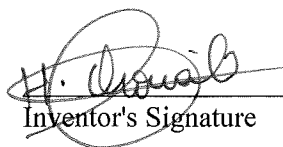
**ASSIGNMENT OF PATENT APPLICATION**

WHEREAS, we, Houssam Chouaib, 2112 Mesa Verde Drive, Milpitas, California 95035; Aaron Rosenberg, 20 Descanso Drive, San Jose, California 95134; Shawn Lin, 1083 NE 47<sup>th</sup> Avenue, Hillsboro, Oregon 97124; Dawei Hu, 8-501, Lane #350, Shanghai, 201114, China; and Zhengquan Tan, 20306 Clifden Way, Cupertino, California 95014, (hereinafter referred to as ASSIGNORS), having post office addresses that follow our names, are the joint inventors of the invention described and claimed in the specification forming part of the United States patent application entitled "Scatterometry Based Methods And Systems For Measurement Of Strain In Semiconductor Structures," which was filed on October 22, 2019, and now has U.S. Application Ser. No. 16/660,492;

WHEREAS, KLA Corporation, (hereafter referred to as ASSIGNEE), a corporation organized under the laws of Delaware and having a place of business at One Technology Drive, Milpitas, California 95035, is desirous of acquiring the entire right, title, and interest in and to the invention and in and to any letters patents that may be granted therefor in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign, and transfer unto said ASSIGNEE, its successors and assigns, the entire right, title, and interest in and to said invention, said application and any and all letters patents which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE, its successors and assigns, and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty, or otherwise, said invention, application and all letters patents on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer, and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patents on said invention to ASSIGNEE, its successors and assigns. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patents on said invention, for litigation regarding said letters patents, or for the purpose of protecting title to said invention or letters patents therefor.

IN WITNESS WHEREOF, We have hereunto signed our names on the day and year set forth below.

  
\_\_\_\_\_  
Inventor's Signature

Houssam Chouaib  
\_\_\_\_\_  
Inventor's Printed Name

10/25/2019  
\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor's Signature

Aaron Rosenberg  
\_\_\_\_\_  
Inventor's Printed Name


\_\_\_\_\_  
Date

Assignment of application entitled: "Scatterometry Based Methods And Systems For Measurement Of Strain In Semiconductor Structures"  
Docket Number: KLA-126 (P5425)

\_\_\_\_\_  
Inventor's Signature

Shawn Lin  
Inventor's Printed Name

\_\_\_\_\_  
Date

  
\_\_\_\_\_  
Inventor's Signature

Dawei Hu  
Inventor's Printed Name

11/05/2019  
Date

\_\_\_\_\_  
Inventor's Signature

Zhengquan Tan  
Inventor's Printed Name

\_\_\_\_\_  
Date

Assignment of application entitled: "Scatterometry Based Methods And Systems For Measurement Of Strain In Semiconductor Structures"  
Docket Number: KLA-126 (P5425)

  
\_\_\_\_\_  
Inventor's Signature

Kai-Hsiang Lin  
\_\_\_\_\_  
Inventor's Printed Name

2019, 11, 12  
\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor's Signature

Dawei Hu  
\_\_\_\_\_  
Inventor's Printed Name

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor's Signature

Zhengquan Tan  
\_\_\_\_\_  
Inventor's Printed Name

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Inventor's Signature

Houssam Chouaib  
Inventor's Printed Name

\_\_\_\_\_  
Date

Aaron Rosenberg  
Inventor's Signature

Aaron Rosenberg  
Inventor's Printed Name

10/25/2019  
Date

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Inventor's Signature                      Houssam Chouaib  
Inventor's Printed Name                      \_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor's Signature                      Aaron Rosenberg  
Inventor's Printed Name                      \_\_\_\_\_  
Date

Assignment of application entitled: "Scatterometry Based Methods And Systems For Measurement Of Strain In Semiconductor Structures"  
Docket Number: KLA-126 (P5425)

\_\_\_\_\_  
Inventor's Signature

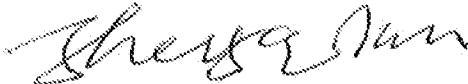
Kai-Hsiang Lin  
Inventor's Printed Name

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor's Signature

Dawei Hu  
Inventor's Printed Name

\_\_\_\_\_  
Date

  
\_\_\_\_\_  
Inventor's Signature

Zhengguan Tan  
Inventor's Printed Name

11/13/2019  
Date